

21. (Amended) An electronic assembly comprising:

an integrated circuit package having a plurality of contacts; [and]  
a substrate having a plurality of lands, each land having a geometric center and an edge,  
each land having a via therein, each via having a geometric center in a region between the  
geometric center and the edge of its associated land [each land having an offset via, and each  
land being aligned with respect to a contact of the integrated circuit package]; and  
a plurality of solder balls, each coupling one of the plurality of contacts to a respective  
one of the plurality of lands, each of the solder balls contacting substantially the entire respective  
land to the edge of such land.

26. Cancelled.

27. (Amended) The electronic assembly recited in claim 21 [26], wherein the geometric centers of vias of adjacent lands are offset from the geometric centers of such lands in the same direction.

28. (Amended) An electronic system comprising an electronic assembly having:

an integrated circuit package having a plurality of pads, [and]  
a substrate having a plurality of lands, each land having a geometric center and an edge,  
each land having a via therein, each via having a geometric center in a region between the  
geometric center and the edge of its associated land [each land being aligned with respect to a  
respective contact of the integrated circuit package and comprising an offset via]; and  
a plurality of solder balls, each coupling one of the plurality of pads to a respective one of  
the plurality of lands, each of the solder balls contacting substantially the entire respective land to  
the edge of such land.